



US00D947813S

(12) **United States Design Patent**
He

(10) **Patent No.:** **US D947,813 S**

(45) **Date of Patent:** **** Apr. 5, 2022**

(54) **OVER EAR HEADPHONES**

(71) Applicant: **Ruiboshi Technology (ShenZhen) Co., Ltd.**, Shenzhen (CN)

(72) Inventor: **Shixing He**, Guangdong (CN)

(73) Assignee: **Ruiboshi Technology (ShenZhen) Co., Ltd.**, Shenzhen (CN)

(**) Term: **15 Years**

(21) Appl. No.: **29/796,660**

(22) Filed: **Jun. 25, 2021**

(51) **LOC (13) Cl.** **14-01**

(52) **U.S. Cl.**
USPC **D14/206; D14/205; D14/226**

(58) **Field of Classification Search**
USPC D14/206, 226, 205, 225, 188, 192;
D29/112; 2/209; 381/380–381, 374;
455/90.3, 575.1, 569.1
CPC H04R 25/00; H04R 25/02; H04R 1/1066;
H04R 1/1016; H04R 5/033; H04R
5/0335; H04R 1/10; H04R 1/1041; H04R
1/1008; H04R 1/1025; H04R 1/105;
H04R 19/04; H04R 1/1091
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

3,488,457 A * 1/1970 Lahti H04R 1/1008
381/376
D254,183 S * 2/1980 Doodson D14/205
D328,074 S * 7/1992 Yamazaki D14/205
D345,361 S * 3/1994 Grasso D14/205
D358,391 S * 5/1995 Isono D14/205
D386,181 S * 11/1997 Fisher D14/195
D394,062 S * 5/1998 Chun D14/197

D423,012 S * 4/2000 Yasutomi D14/205
6,081,604 A * 6/2000 Hikichi H04R 5/0335
381/124
D439,574 S * 3/2001 Katayama D14/203.5
(Continued)

FOREIGN PATENT DOCUMENTS

CN 306760851 * 8/2021
CN 306855426 * 9/2021
(Continued)

Primary Examiner — Paula Allen Greene

(74) *Attorney, Agent, or Firm* — ScienBiziP, P.C.

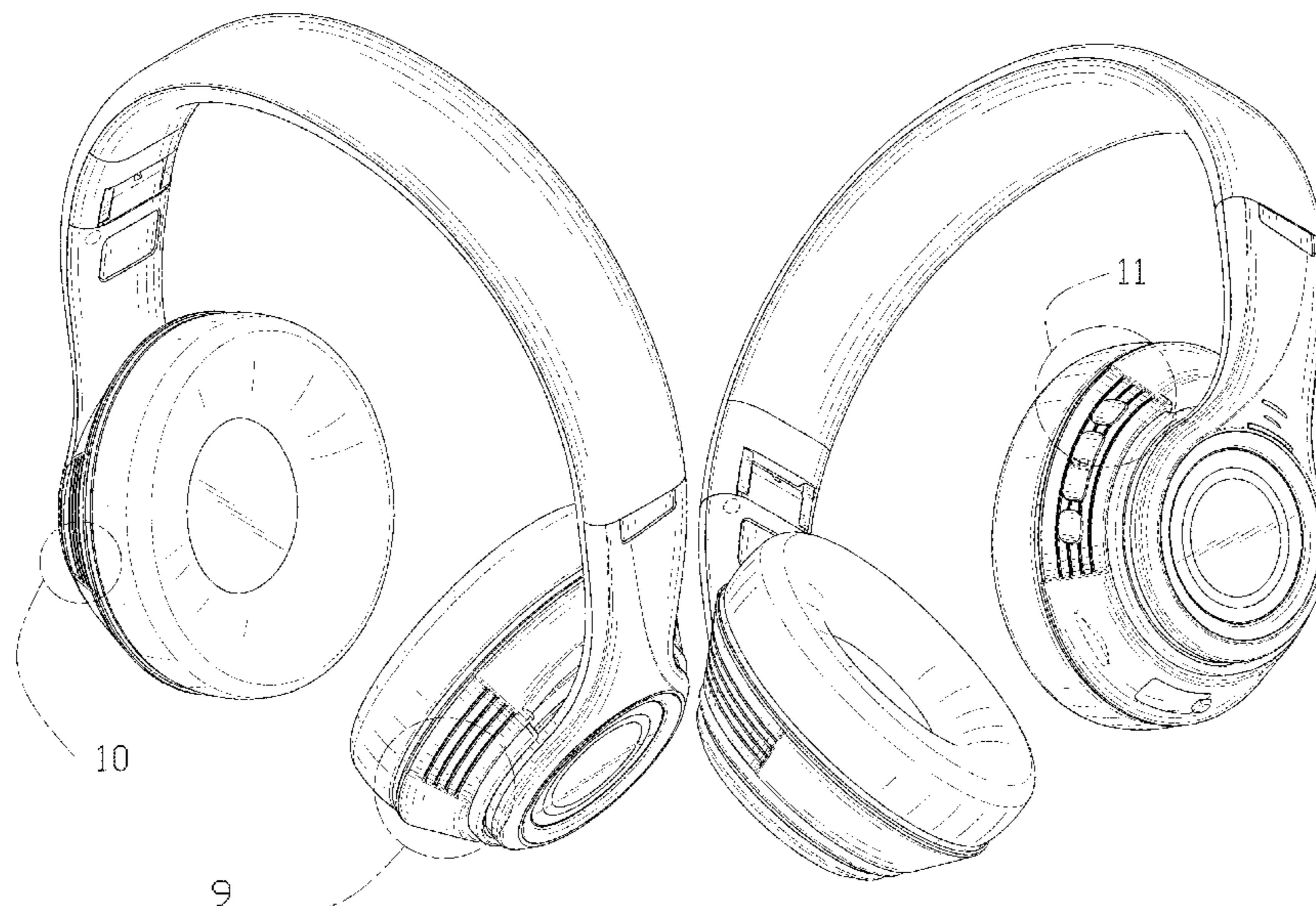
(57) **CLAIM**

The ornamental design for an over ear headphones, as shown and described.

DESCRIPTION

FIG. 1 is a front, right, and top perspective view of an over ear headphones, showing my design.
FIG. 2 is a rear, left, and bottom perspective view thereof.
FIG. 3 is a front elevation view thereof.
FIG. 4 is a rear elevation view thereof.
FIG. 5 is a left side elevation view thereof.
FIG. 6 is a right side elevation view thereof.
FIG. 7 is a top plan view thereof.
FIG. 8 is a bottom plan view thereof.
FIG. 9 is a partial enlarged view of an area labeled 9 in FIG. 1 comprising a right headset part.
FIG. 10 is a partial enlarged view of an area labeled 10 in FIG. 1 comprising a left headset part; and,
FIG. 11 is a partial enlarged view of an area labeled 11 in FIG. 2 comprising a left headset part.
The broken lines shown in the drawings are included for the purpose of illustrating portions of the over ear headphones that form no part of the claimed design.
The dot-dash-dot broken lines encircling portions of the over ear headphones in FIGS. 1 and 2 and illustrated in enlarged views of FIGS. 9 through 11 form no part of the claimed design.

1 Claim, 11 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

D484,485 S * 12/2003 Matsuoka D14/205
 D652,406 S * 1/2012 Lee D14/205
 D671,914 S * 12/2012 Lee D14/205
 D673,518 S * 1/2013 Tan D14/205
 D673,520 S * 1/2013 Tan D14/205
 D677,647 S * 3/2013 Lee D14/205
 D691,984 S * 10/2013 Wang D14/205
 D700,904 S * 3/2014 Miller D14/218
 D708,162 S 7/2014 Wenger et al.
 D716,760 S * 11/2014 Brunner D14/206
 D729,196 S 5/2015 Liu
 D732,000 S * 6/2015 Brunner D14/205
 D738,350 S * 9/2015 Brunner D14/205
 D791,733 S * 7/2017 Brunner D14/205
 D800,691 S * 10/2017 Ando D14/205
 D811,364 S * 2/2018 Park D14/205
 D814,440 S * 4/2018 Hardi D14/205
 D823,278 S * 7/2018 Ito D14/205
 D826,210 S * 8/2018 Chong D14/205
 D834,260 S * 11/2018 Garcia Mansilla D29/112
 D836,084 S * 12/2018 Xie D14/205
 D840,370 S * 2/2019 Kelly D14/205
 D852,163 S * 6/2019 Nagamine D14/205
 D852,775 S * 7/2019 Ando D14/205
 D857,652 S * 8/2019 Wang D14/205
 D858,483 S * 9/2019 Hu D14/205
 D859,354 S * 9/2019 Xia D14/205
 D860,161 S * 9/2019 Xia D14/205
 D868,731 S * 12/2019 Jung D14/205
 D868,733 S * 12/2019 Luo D14/205

D869,437 S * 12/2019 Hu D14/205
 D876,388 S * 2/2020 Carr D14/205
 D877,114 S * 3/2020 Lindenberger D14/205
 D879,742 S * 3/2020 Hu D14/205
 D883,949 S * 5/2020 Hu D14/205
 D886,078 S * 6/2020 He D14/206
 D888,008 S * 6/2020 Yook D14/205
 D889,432 S * 7/2020 Brunner D14/205
 D892,079 S * 8/2020 Wu D14/205
 D893,452 S * 8/2020 Yook D14/205
 D894,867 S * 9/2020 Choe D14/205
 D904,339 S * 12/2020 Wang D14/205
 D910,594 S * 2/2021 Chen D14/206
 D918,172 S * 5/2021 Jaques D14/206
 D927,453 S * 8/2021 Smiechowski D14/205
 D941,262 S * 1/2022 Brunner D14/206
 2010/0310093 A1 * 12/2010 Semcken H04R 1/1058
 381/104
 2011/0206215 A1 * 8/2011 Bunk G06F 1/1694
 381/74
 2011/0206216 A1 * 8/2011 Brunner H04R 1/1066
 381/74
 2019/0230429 A1 * 7/2019 Bozaglo H04R 5/033
 2020/0252710 A1 * 8/2020 Bottoni H04R 1/26
 2020/0389719 A1 * 12/2020 Morris H04R 1/1008
 2021/0084401 A1 * 3/2021 Smiechowski H04R 1/1025

FOREIGN PATENT DOCUMENTS

CN 306855427 * 9/2021
 EM 008837843-0001 * 1/2022
 JP D1673628 * 11/2020

* cited by examiner

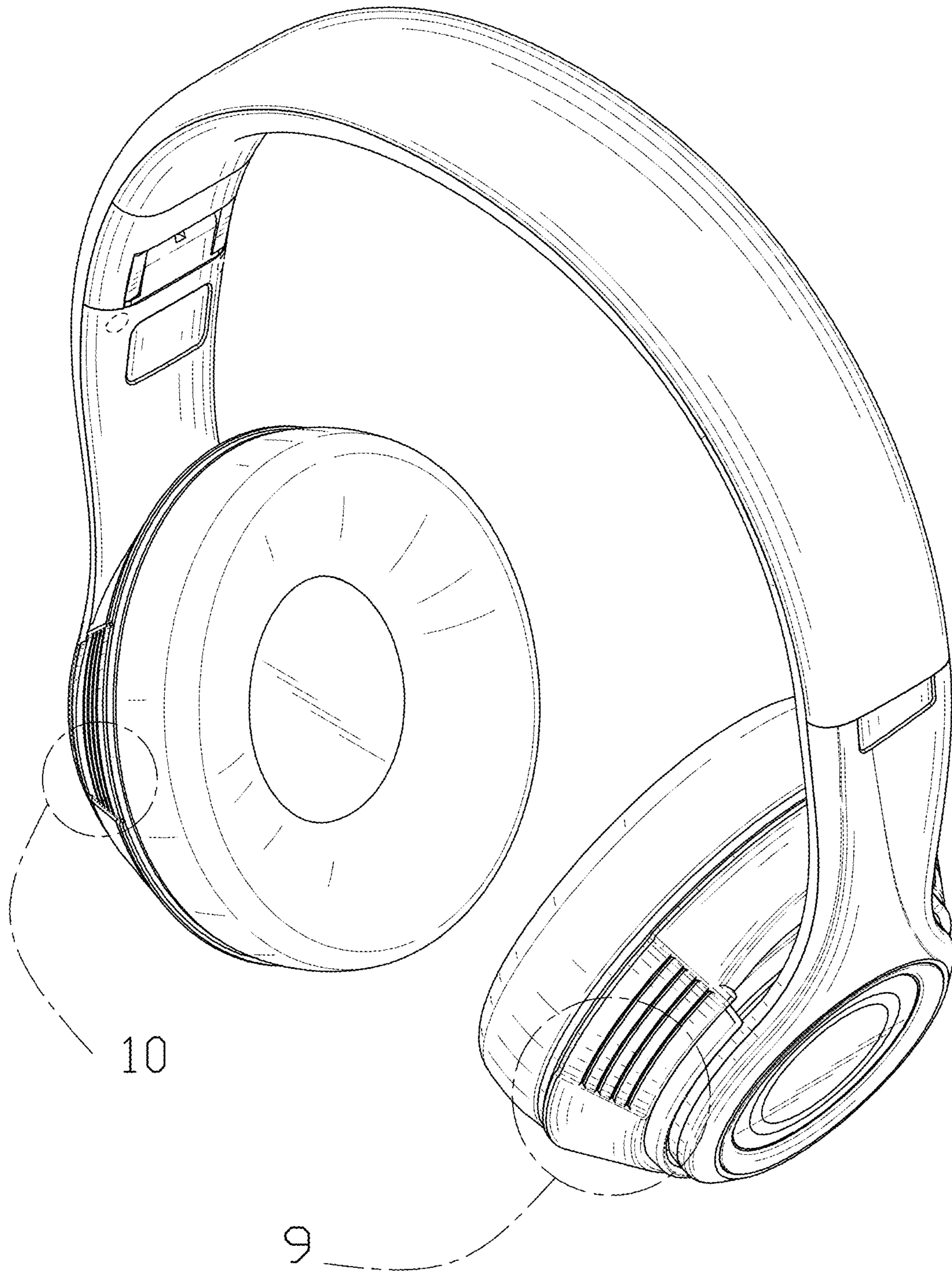


FIG. 1

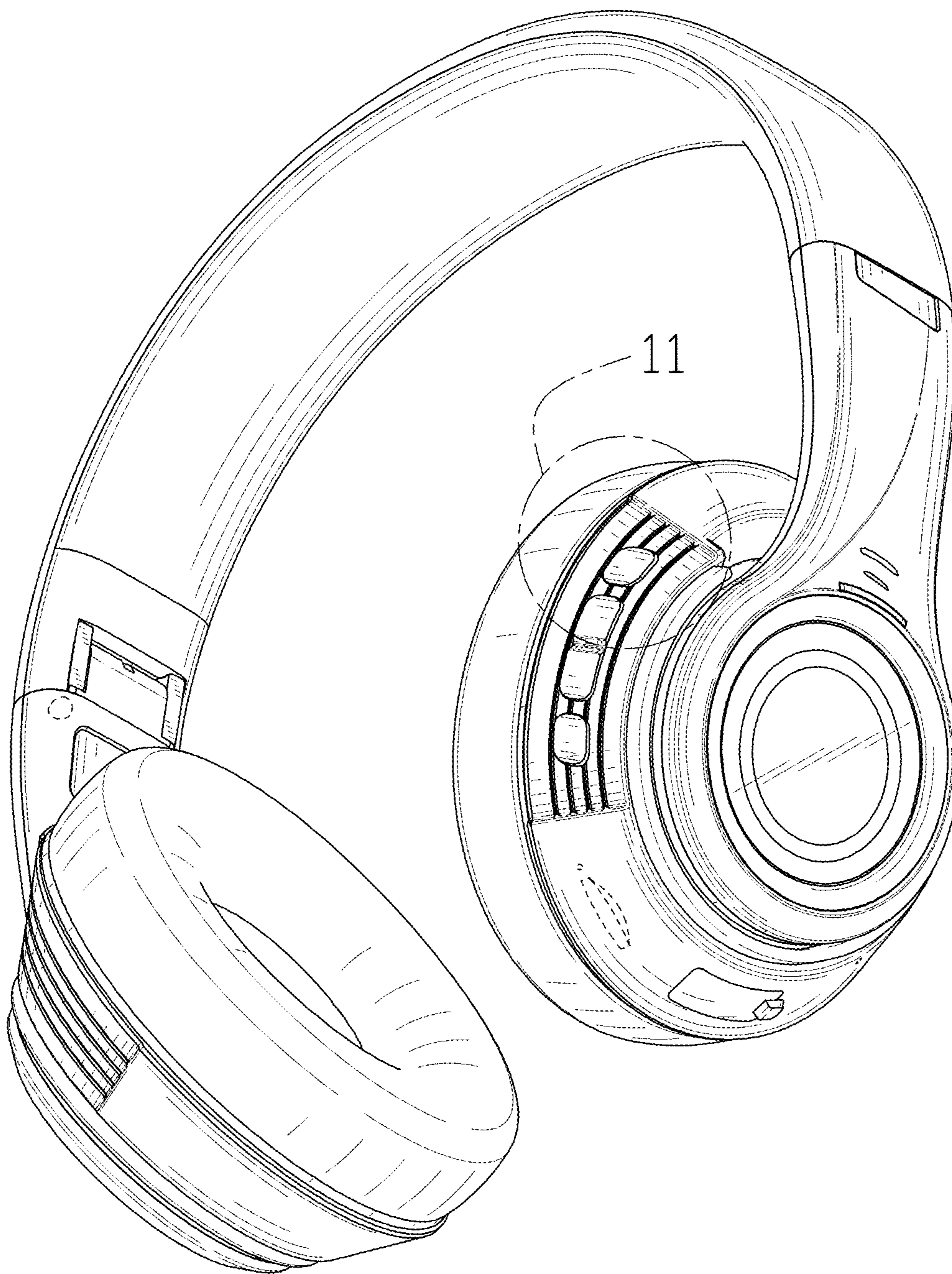


FIG. 2

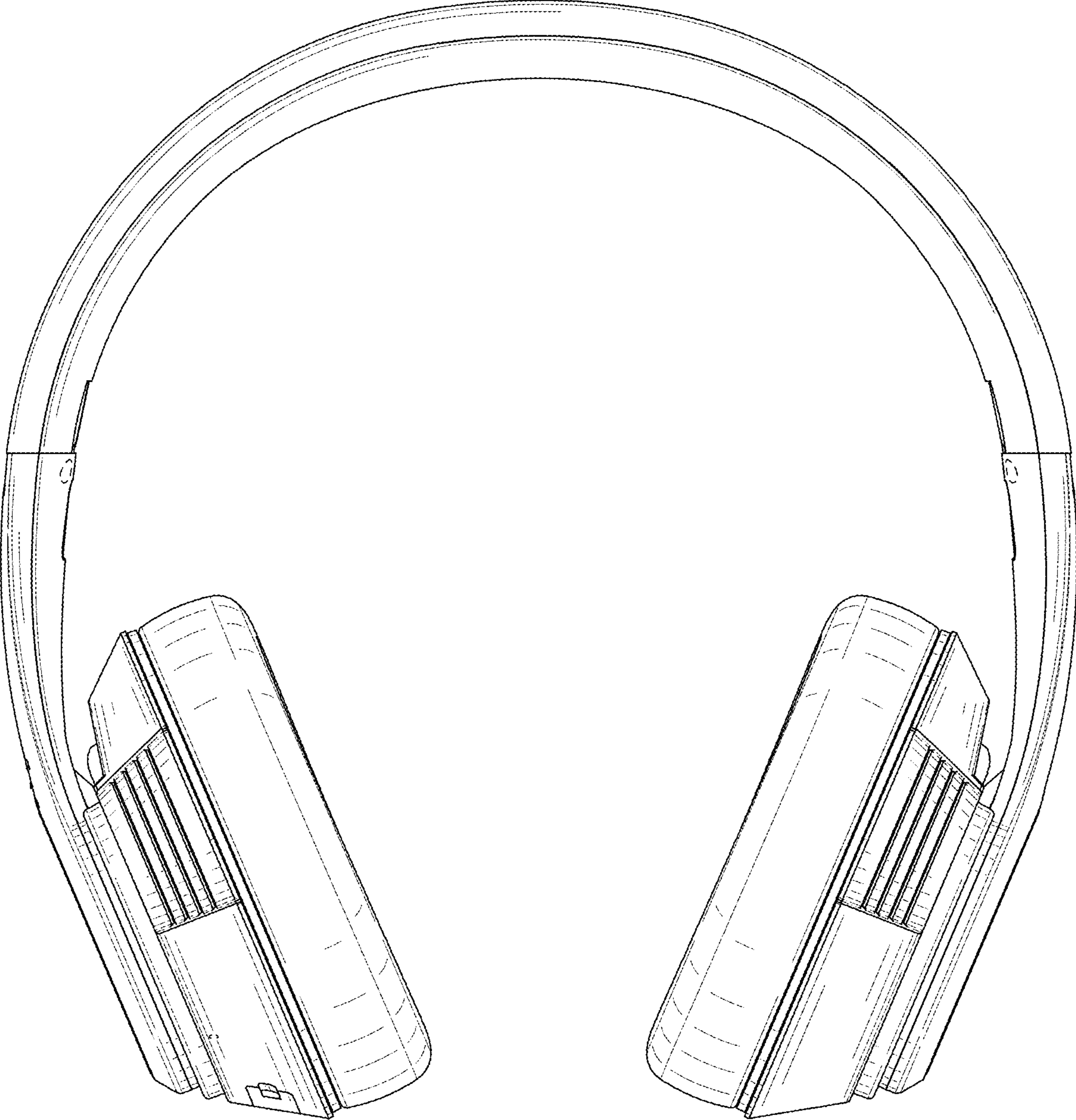


FIG. 3

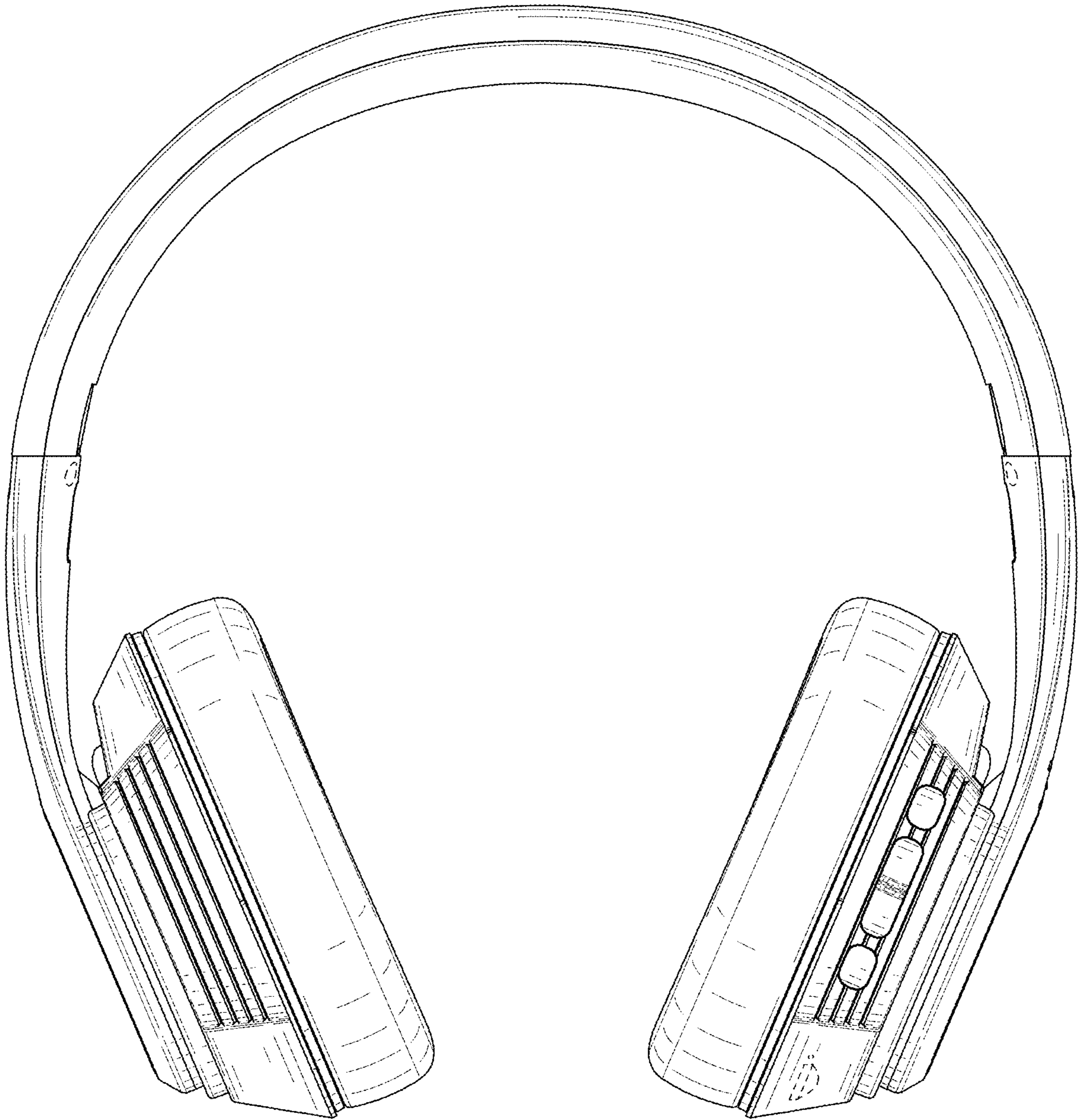


FIG. 4

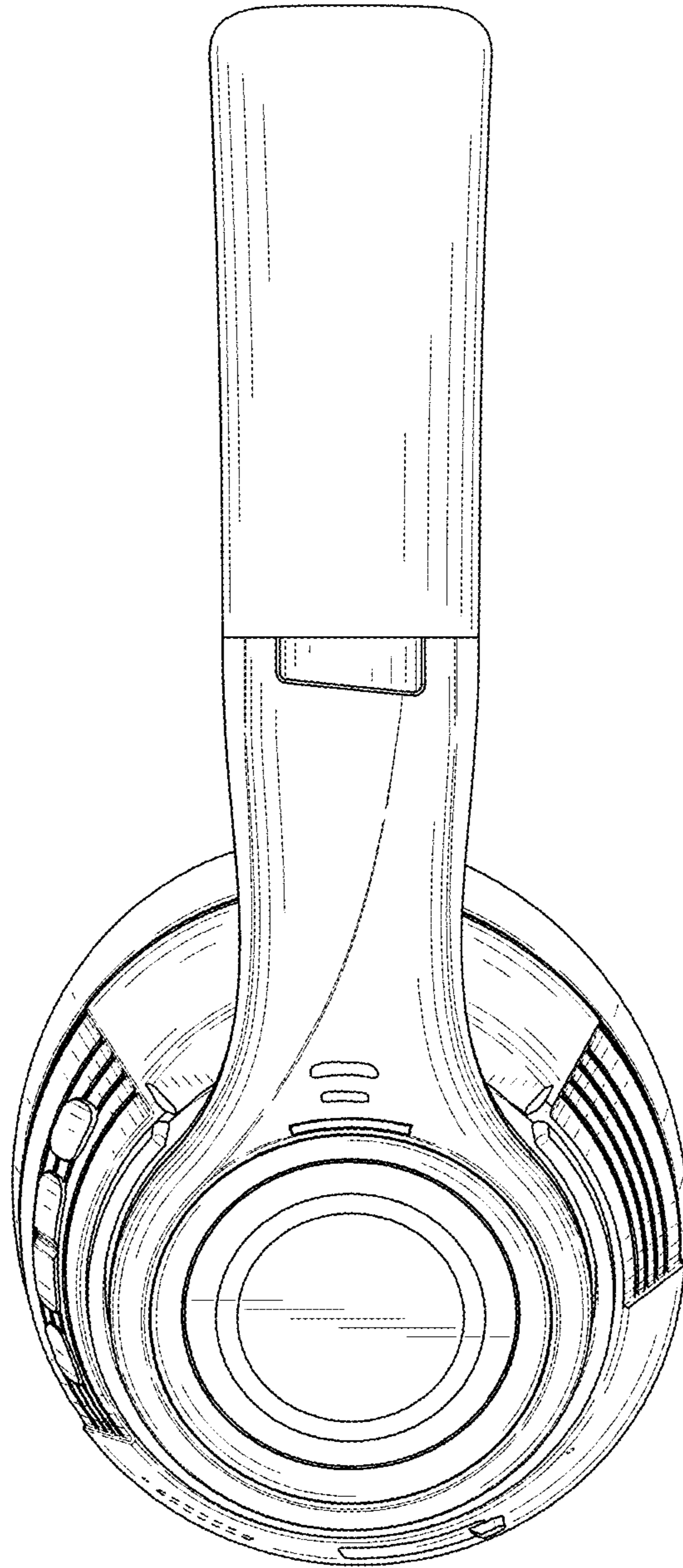


FIG. 5

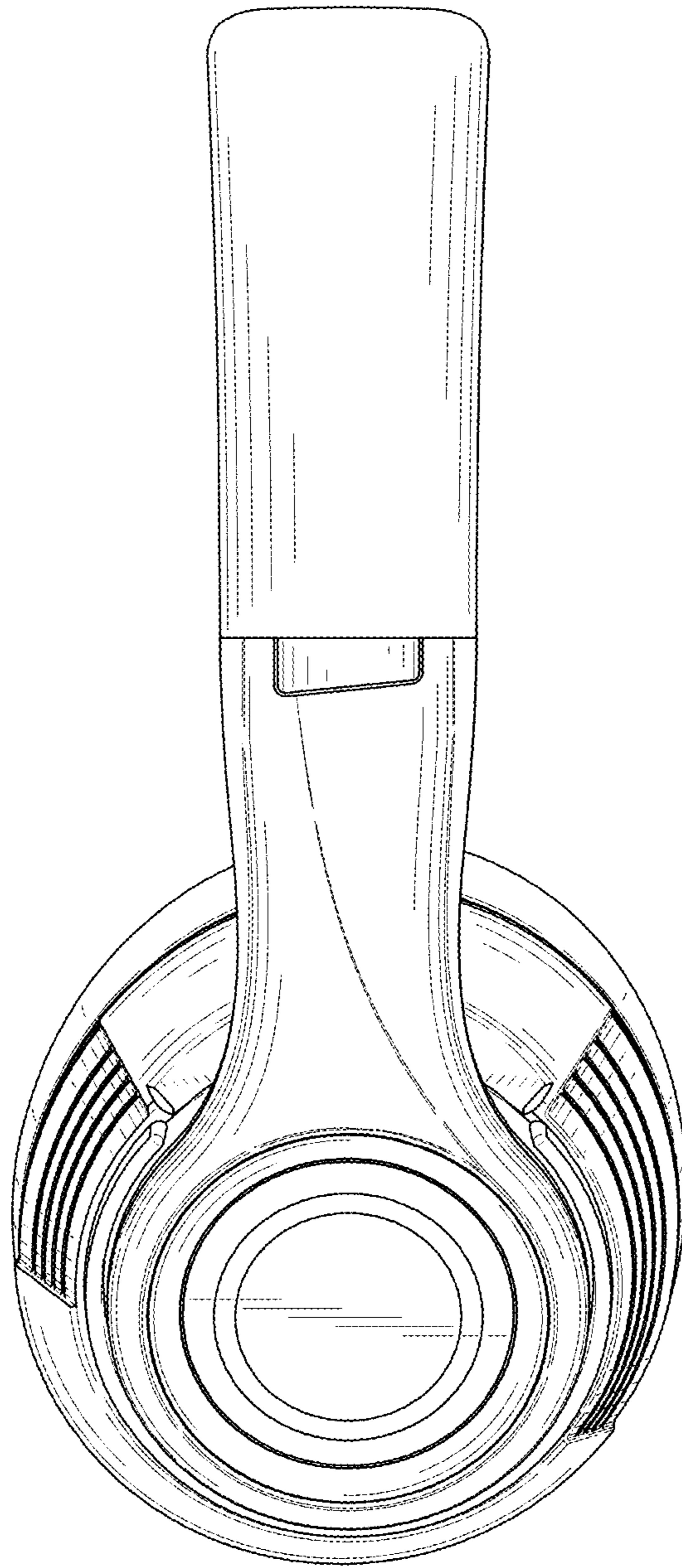


FIG. 6

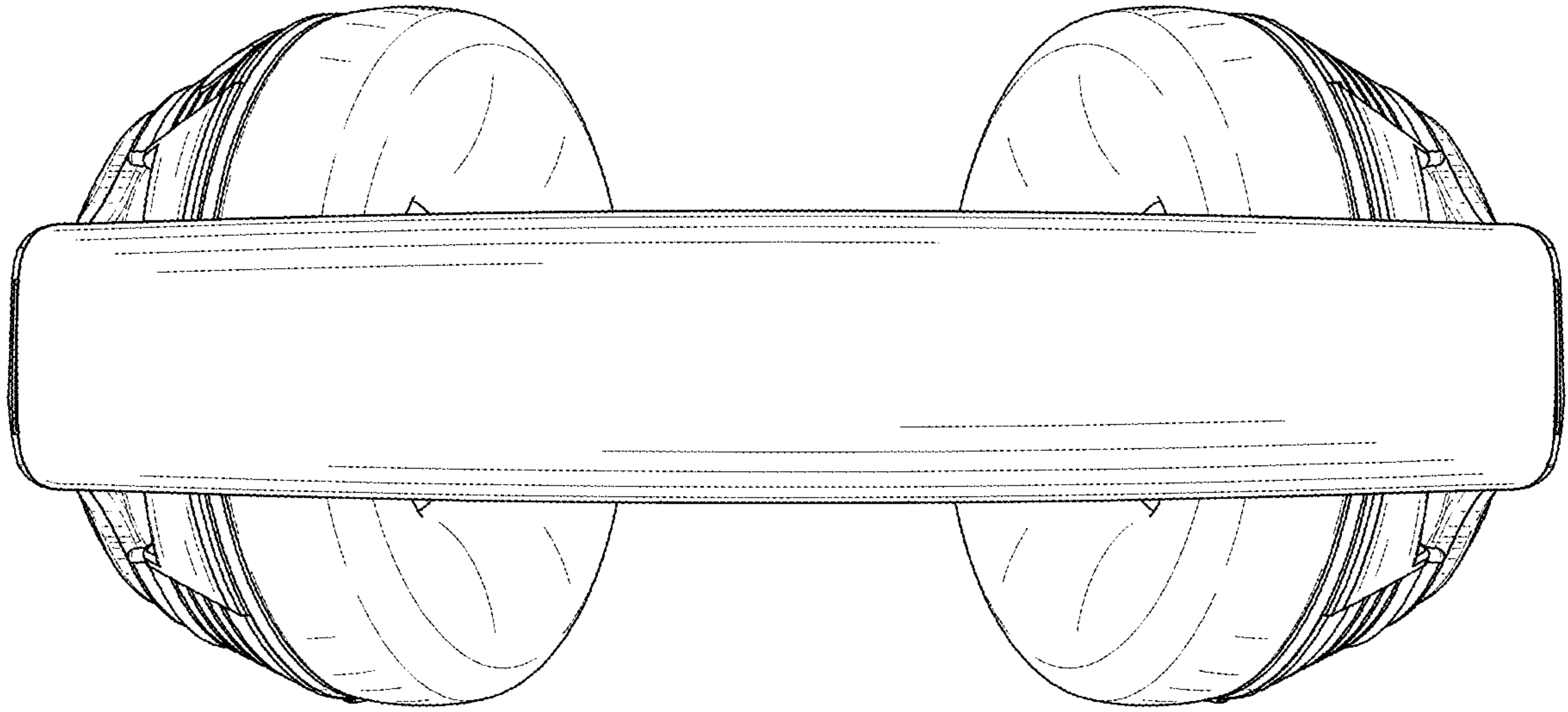


FIG. 7

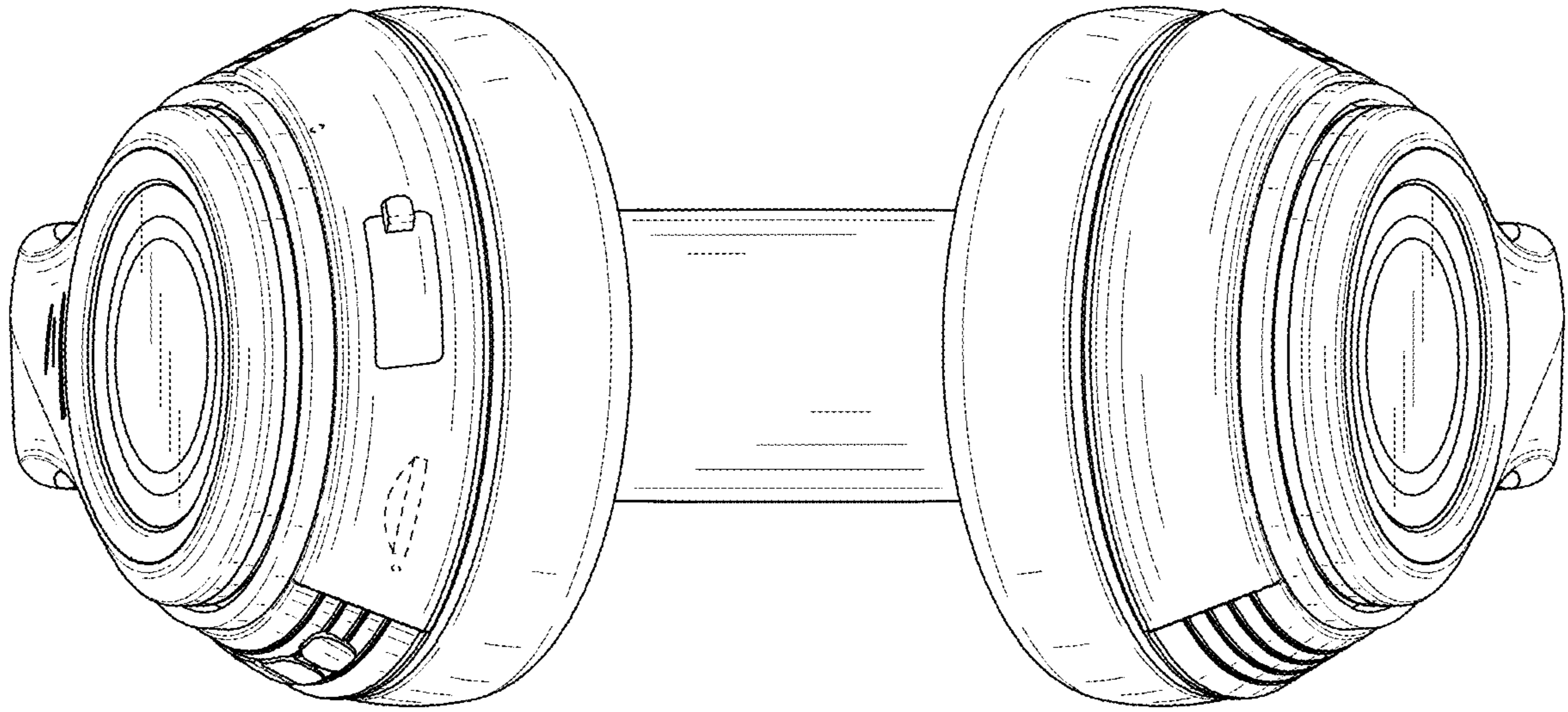


FIG. 8

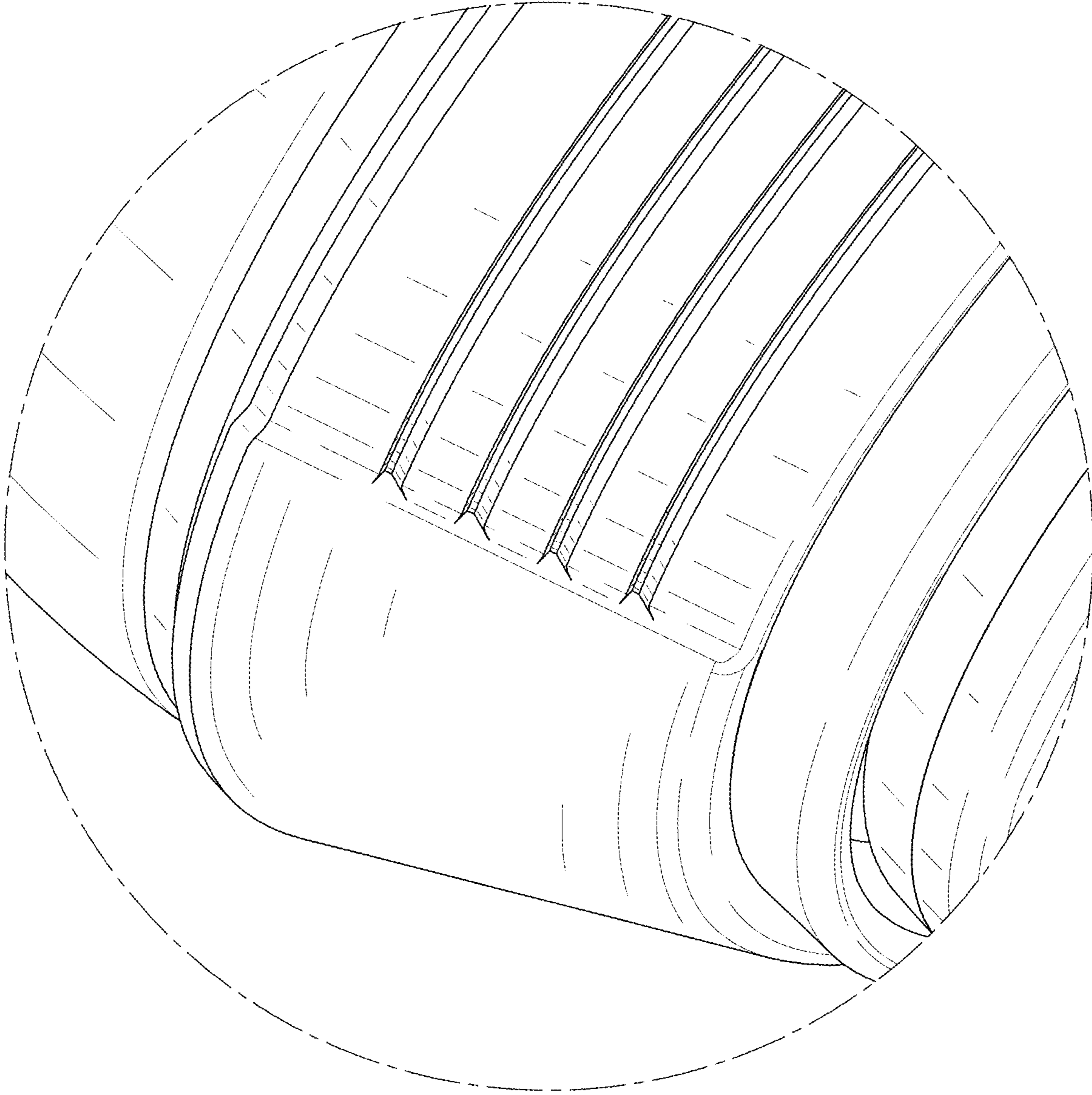


FIG. 9

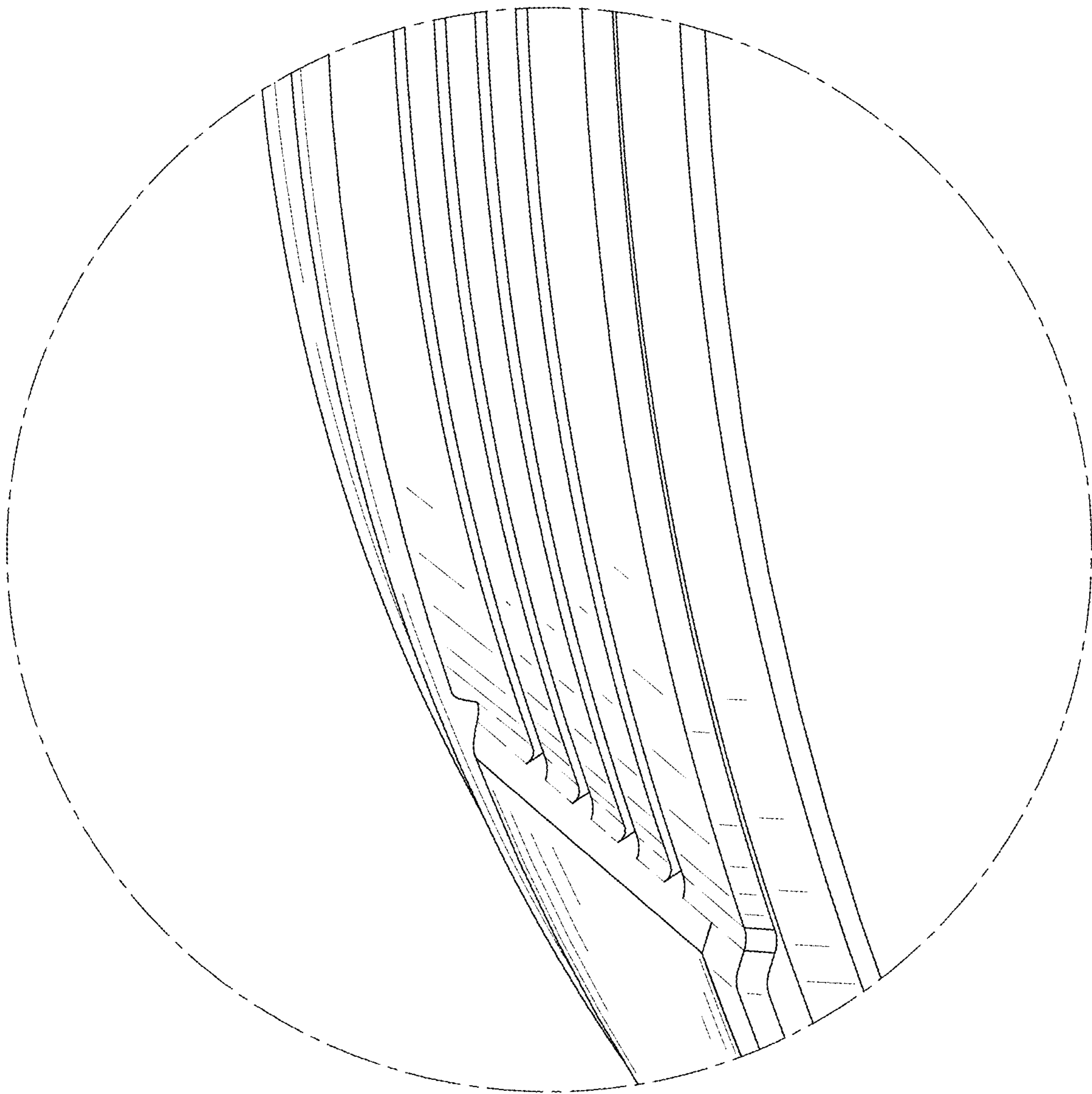


FIG. 10

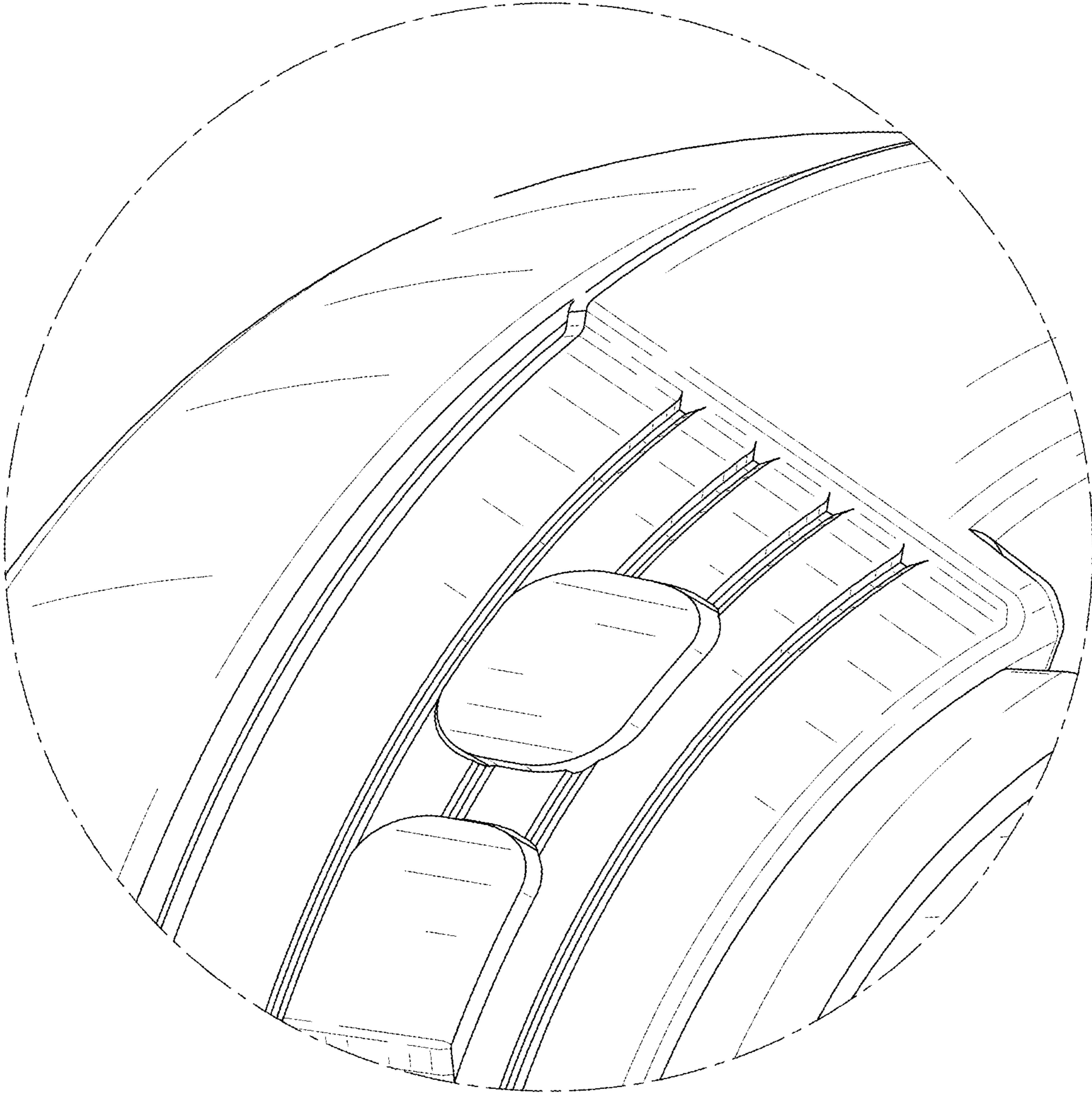


FIG. 11